CLAIMS

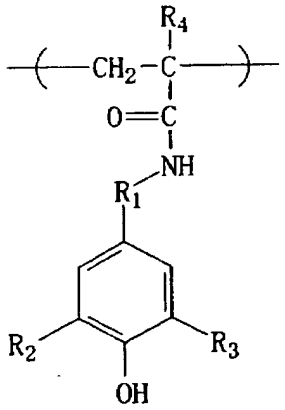
1. A two-layer laminated film for forming bumps, comprising:

(I) a lower layer comprising a composition including a polymer (A) and an organic solvent (B); and

(II) an upper layer comprising a negative radiation-sensitive resin composition;

the polymer (A) including a structural unit represented by Formula (1):

[Chem. 1]



....(1)

wherein R_1 is $-(CH_2)_n-$ where n is an integer of 0 to 3, and R_2, R_3 and R_4 are the same or different from one another and are each a hydrogen atom or an alkyl group of 1 to 4 carbon atoms.

2. The two-layer laminated film for forming bumps according to claim 1, wherein the negative radiation-sensitive resin composition for the upper layer (II) includes a polymer having a carboxyl group and/or a phenolic hydroxyl group (C), a crosslinking agent (D), a radiation-activated radical polymerization initiator (E), and an organic solvent (F).

3. The two-layer laminated film for forming bumps according to claim 2, wherein the polymer (C) has a glass transition temperature (Tg) of not less than 40°C.

4. A transfer film comprising the laminated film claimed in claim 1 and a support film on which the laminated film is provided.

5. A process for forming bumps on electrode pads on a wiring board, comprising at least:

(a) a step of providing the two-layer laminated film claimed in claim 1 on a substrate and forming a pattern of apertures at positions corresponding to electrode pads;

(b) a step of introducing a low-melting metal in the apertures;

(c) a step of reflowing the low-melting metal by heating to form bumps; and

(d) a step of peeling and removing the two-layer laminated film from the substrate.

6. A process for forming bumps on electrode pads on a wiring board, comprising at least:

(a) a step of providing the two-layer laminated film claimed in claim 1 on a substrate and forming a pattern of apertures at positions corresponding to electrode pads;

(b) a step of introducing a low-melting metal in the apertures;

(d') a step of peeling and removing the two-layer laminated film from the substrate; and

(c') a step of reflowing the low-melting metal by heating to form bumps.